

Reliability Monitoring Results

Quarters: Q1/2024 to Q4/2024

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		74LVC1G38GV				
Part Description: Single 2-input NAND gate; open-drain						
Function Family: LVC Process family: Sub micron Package family: TSOP						
JESD47 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects
# 1	TEST Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# 2	PC Preconditioning	JESD22-A113 MSL 1	N/A	188	15141	0
# 5a	HTOL EFR High Temperature Operating Life Extrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} ≤ V ≤ 1.2*V _{CCMAX}	48 hours or 168 hours	405	62852	0
# 5b	HTOL IFR High Temperature Operating Life Intrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} ≤ V ≤ 1.2*V _{CCMAX}	≥500 hours	180	13480	0
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to 150°C	≥500 cycles	90	7176	0
# 9	uHAST / HAST unbiased or biased High Accelerated Stress Test	JESD22-A101 Tamb = 130 °C, RH = 85%, V = V _{CCMAX}	96 hours	100	7965	0

Calculation of PPM, FIT and MTTF

Test considered for PPM calculation: High Temperature Operating LifeTest Extrinsic (HTOL EFR, Test # 5a above)
 Test considered for FIT and MTTF calculations: High Temperature Operating LifeTest Intrinsic (HTOL IFR, Test # 5b above)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Product Family	Package Family	Quantity	Rejects	Extrinsic Failure Rate (PPM)	Intrinsic Failure Rate (FIT)	MTTF (hrs)
LVC	TSOP	13480	0	15	0.4	3.33 E+09